

LNJ03004BLD1

Surface Mounting Chip LED

3230 Type

Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	430	mW
Forward current* ¹	I_F	120	mA
Pulse forward current* ²	I_{FP}	200	mA
Junction temperature	T_j	110	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Lighting Color

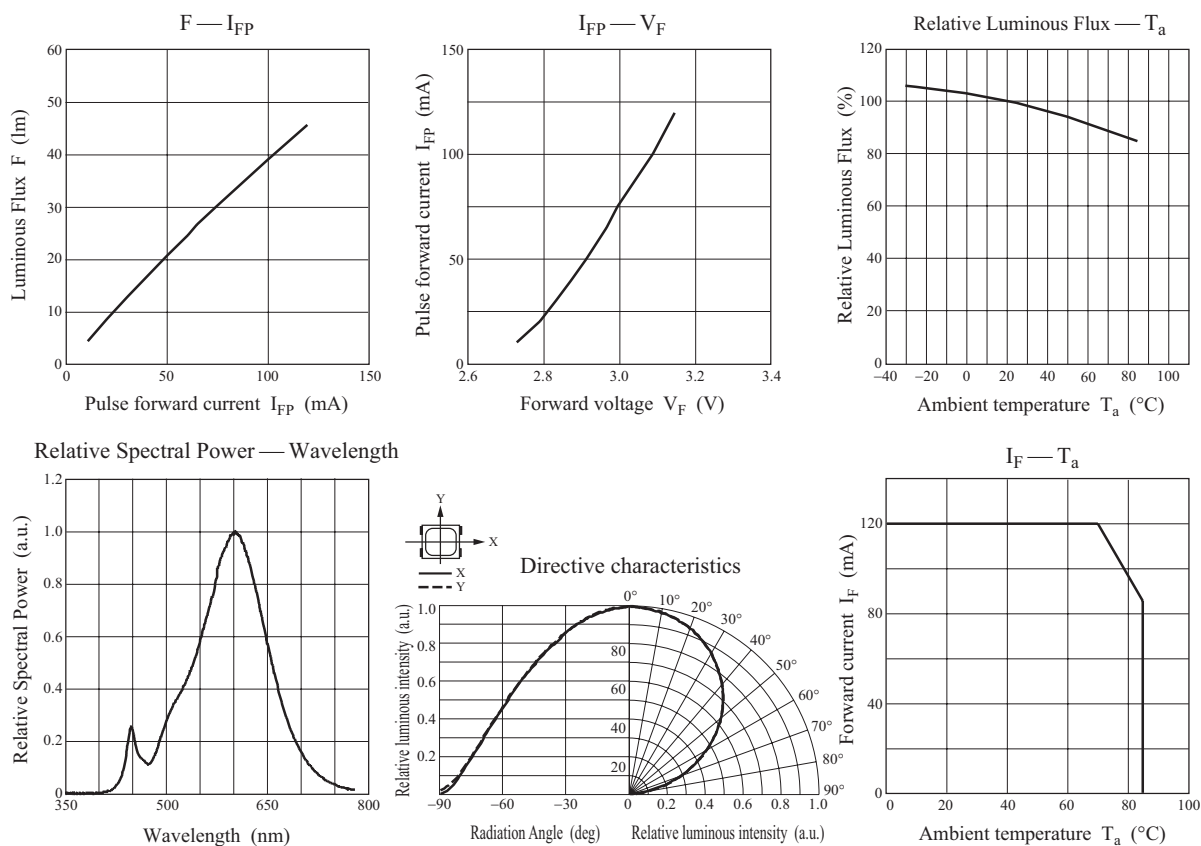
- White (2700 [Kelvin])

Note) *1: I_F is different by radiated factor of evaluation board.
This value is mounted on evaluation board at $R_{th-j-a} = 25.0^\circ\text{C/W}$.
*2: The condition of pulse current I_{FP} is 55 ms pulse width, 10 % duty.

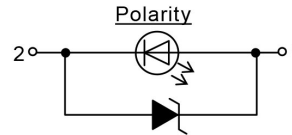
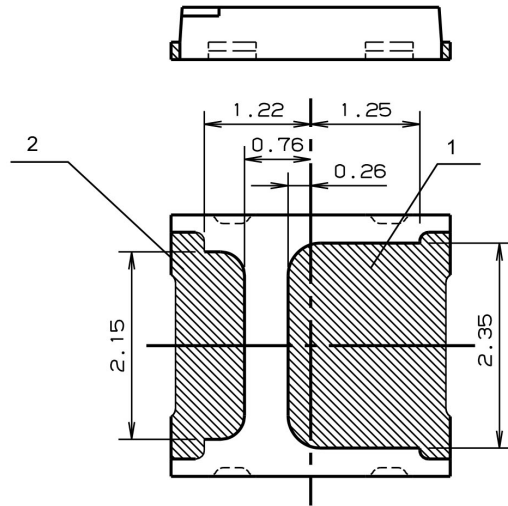
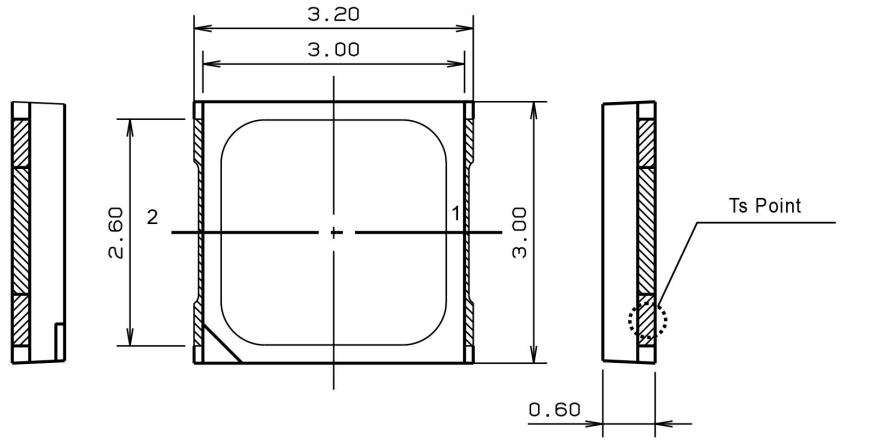
Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage* ¹	V_F	$I_{FP} = 60\text{ mA}$	2.7	2.95	3.2	V
Luminous flux* ²	F	$I_{FP} = 60\text{ mA}$	20.0	24.7	28.0	lm
Chromaticity coordinates* ³	x	$I_{FP} = 60\text{ mA}$		0.459		—
	y	$I_{FP} = 60\text{ mA}$		0.412		—
Color Rendering Index	Ra	$I_{FP} = 60\text{ mA}$		82		—

Note) *1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance $\pm 3\%$
*2: Complete Luminous flux measurement within 0.1 seconds. Tolerance $\pm 10\%$
*3: Complete Chromaticity coordinates measurement within 0.1 seconds. Tolerance of chromaticity is ± 0.01



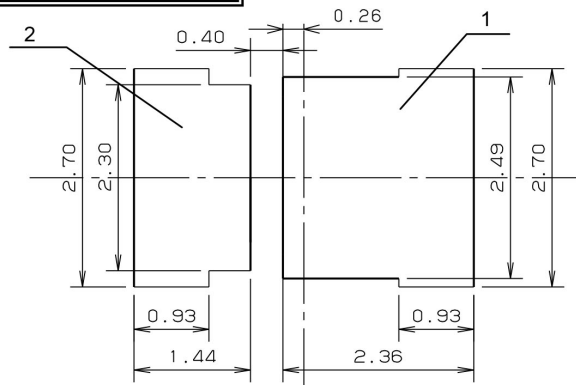
■ Package (Unit: mm)



1. Anode
2. Cathode

Item	Contents
Terminal Process	Cu + Ag Plate
Mold Material	Silicone Resin
Package Material	Polymer Base Reflection case

Reference Land Layout



(Note1) Tolerance unless otherwise specified : $\pm 0.2\text{mm}$

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